

Figure 1



Figure 2

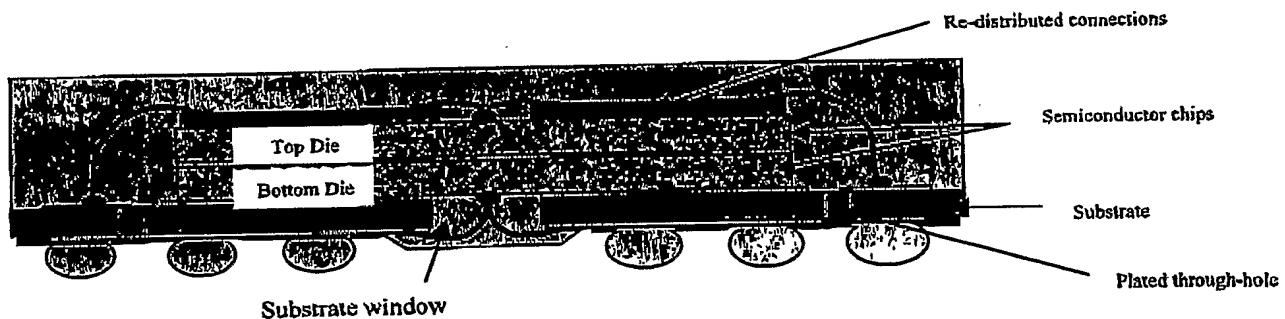


Figure 3

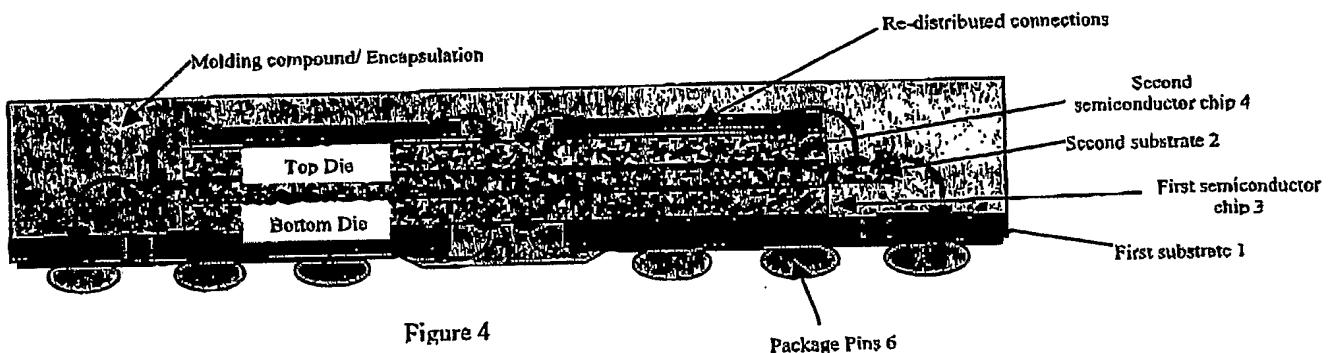
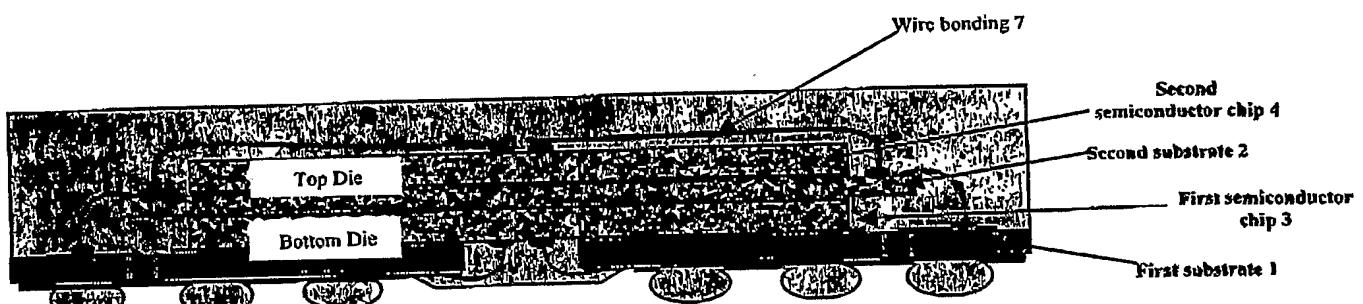
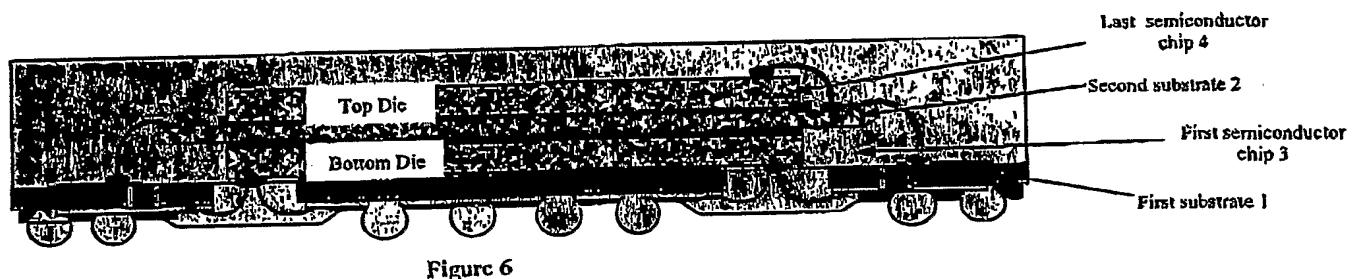
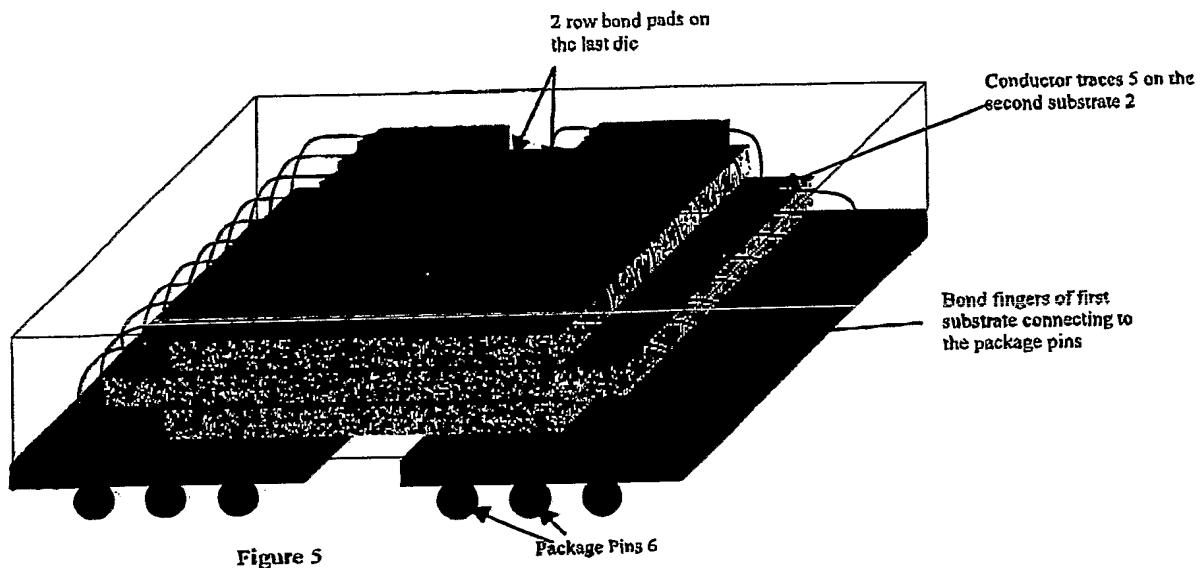
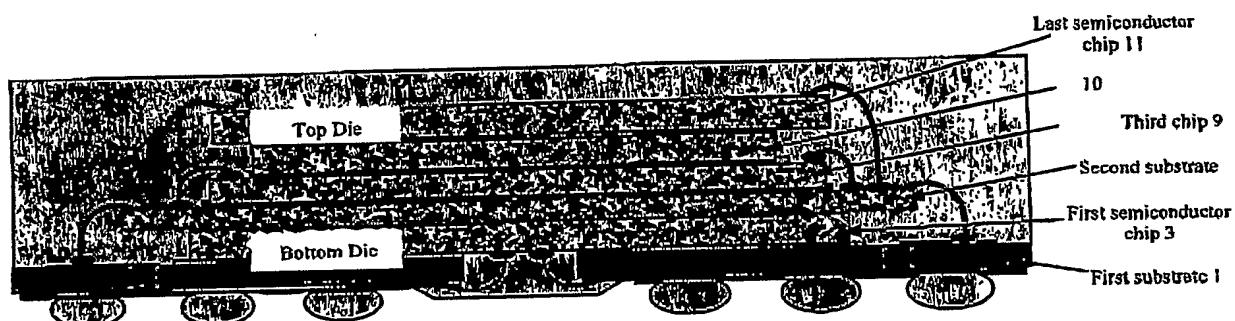
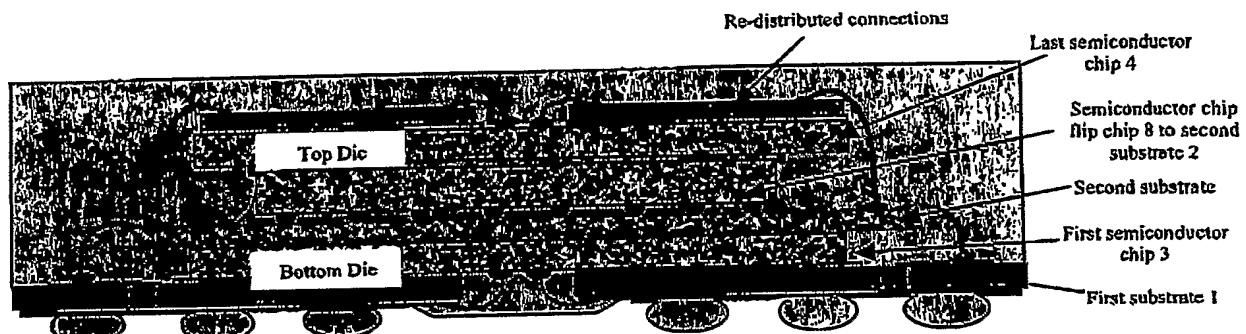
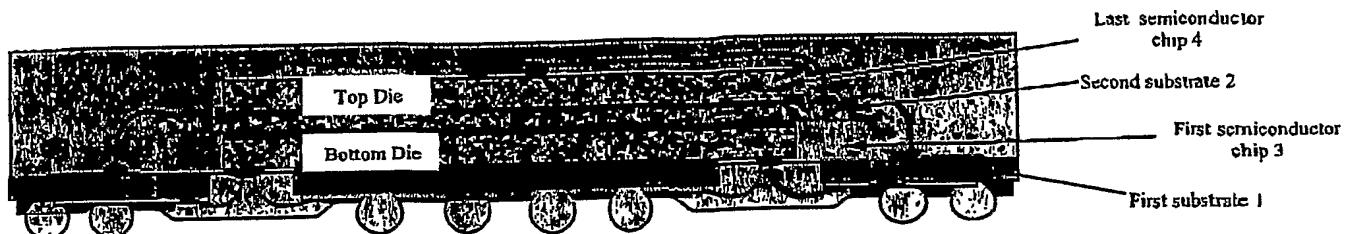


Figure 4





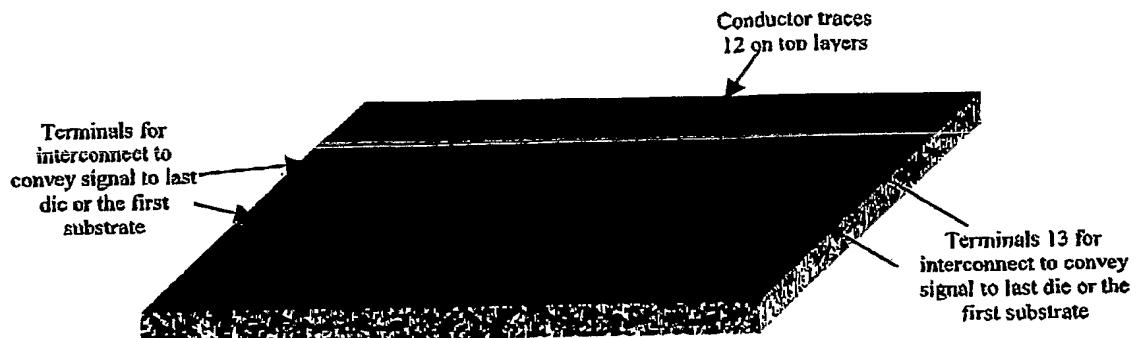


Figure 11A

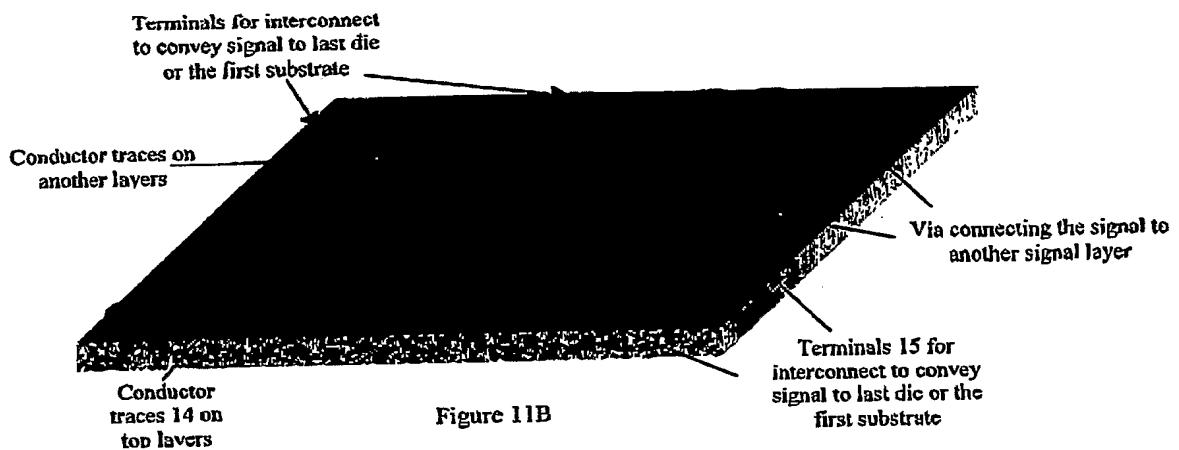


Figure 11B

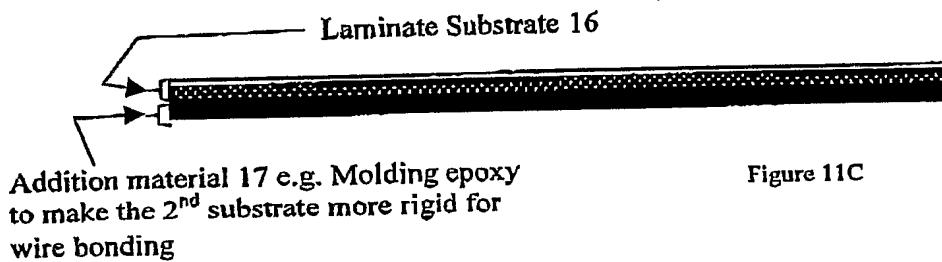


Figure 11C

Figure 12: Method of Manufacture (1/2)

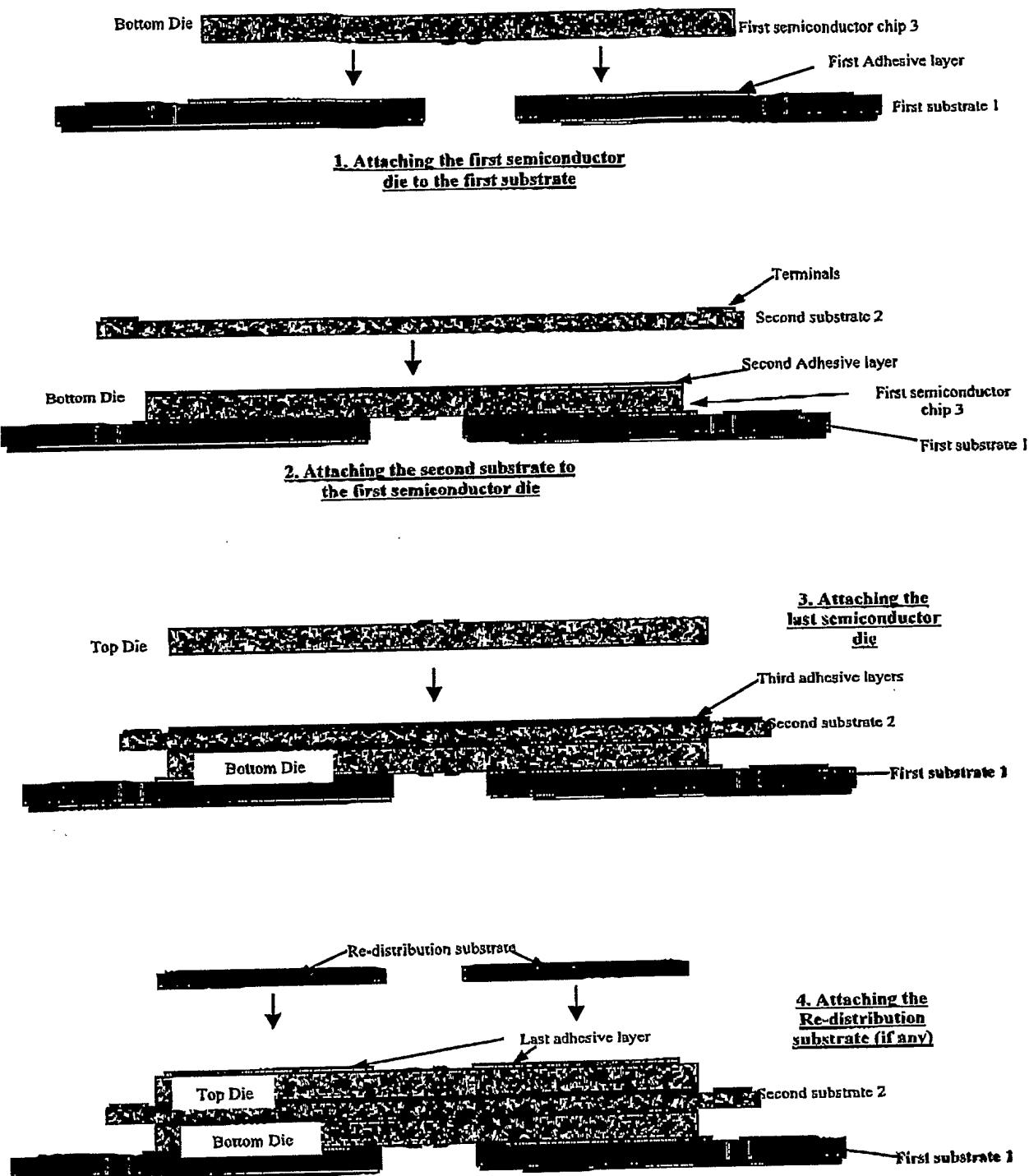
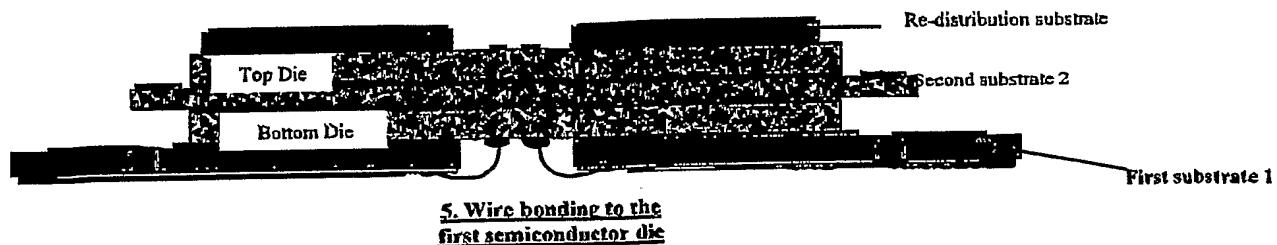
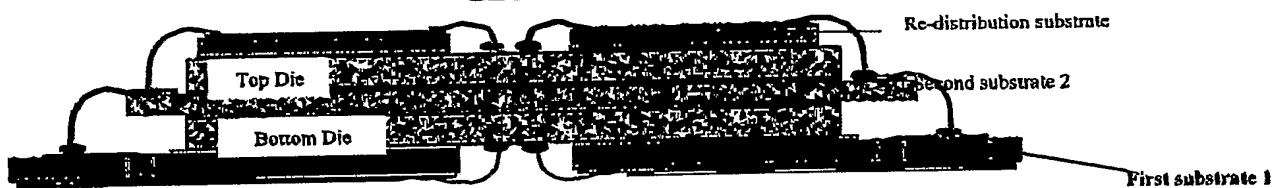
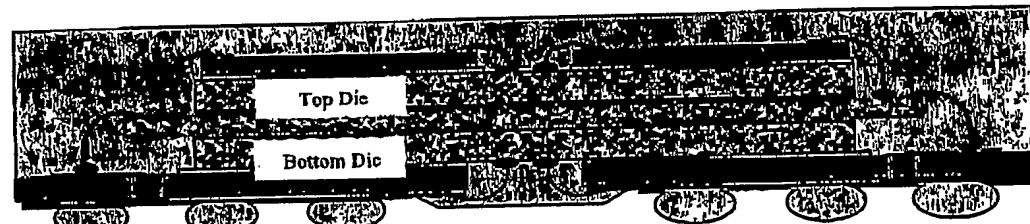


Figure 12: Method of Manufacture (2/2)

6. Wire bonding on the die side of the first substrate7. Transfer molding on both the die side and solder ball side of the first substrate at the same time8. Solder ball attach to the first substrate